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CONTENT

PLENARY SESSION

Technical Program Committee Chair: Yi-Jen Chan (ITRI, Taiwan)

0-1 Innovative Substrate Technologies for New Products	
Rolf Aschenbrenner	3
0-2 Thermal Packaging Challenges and Opportunities at the Micro and Nano Scales	
Avram Bar Cohen	7
0-3 MEMS for Practical Applications with Attention to Packaging	
Masayoshi Esashi	11
0-4 The 3rd dimension—More Life for Moore’s Law	
Douglas C.H. Yu	15

SESSION I : Advanced Packaging Technology

Session Chair: Robert Lo (ITRI, Taiwan)

1-1 Strategies for Embedding of Active Components	
A. Ostmann, D. Manassis, T. Loehner, A. Neumann, H. Reichl	23
1-2 Thermal Stress Analysis of Cu/Low-k Interconnects in 3D-IC Structures	
M. C. Hsieh*, Yung-Yu Hsu, Chao-Liang Chang	27
1-3 Interconnection of Flexible Electronic-Optical Circuit Board Module	
Hsiang-Hung Chang, Li-Cheng Shen, Wei-Chung Lo, Huan-Chun Fu, Yuan-Chang Lee, Shu-Ming Chang Yu-Chih Chen, Wun-Yan Chen	31
1-4 Thermal Evaluations of FCBGA with Embedded Hot Spot Designs	
Eason Chen, Jeng-Yuan Lai, Yu-Po Wang, C.S. Hsiao	35
1-5 Stress and Thermal Characteristic Analyses for Advanced FCBGA Packages	
Yuan Lin Tzeng, Eason Chen, Jeng Yuan Lai, Yu Po Wang, C.S. Hsiao	39
1-6 Embedded Wide-Band Filter on Rigid / Flex. Multilayer PCB for SiP	
Syun Yu, Chang-Sheng Chen, Chang-Lin Wei, Cheng-Hua Tsia, Uei-Ming Jow, Chin-Sun Shyu Sinn-Juh Lay, Min-Lin Lee	43
1-7 Capacitor and coupled inductor with high process tolerance in LTCC	
Hsin-Chia Lu, Tzu-Wei Chao	47

SESSION II : Microsystems Integration

Session Chair: Masayoshi Esashi (Tohoku University, Japan)

2-1 Optimal Design of Optical Fiber-Holding Microclips in Silicon V-Grooves	
W.N. Liu, X. Sun, F. G. Shi	53
2-2 A High Sensitively CMOS Preamplifier for Silicon Microphone	
Lu-Po Liao, Wen-Chieh Chou, Yu-Chun Hsu	57

2-3 Modulation/ Demodulation System for Capacitive Sensors	
Wen-Chieh Chou, Yu-Chun Hsu, Lu-Po Liao	61
2-4 Low Power Consumption PZT Actuated Micro-Pump	
Chou-Lin Wu, Jinn-Cherng Yang, Ying-Chi Chen	65
2-5 No Back-pressure Effect Micro-dispenser Suction Pump	
Chun-Fu Lu, Jinn-Cherng Yang, Chien-Chung Fu	69
2-6 A study of High Sensitive Diaphragm for Silicon Microphone Applications	
Ray-Hua Horng, Zong-Ying. Lin, Yu-Ning Jiang, Shang-Hua You, Shu-Zhen Zhun, Ru-Guan Wang	
Shao-Chih Chang, Tsun - I Tsai, Chung-Chi Lai, Chi-Liang Chen	73
2-7 Drop Directionality of a Thermal Bubble Jet Print Head	
Wei-Liang Hsu, Jinn-Cherng Yang, Wu-Li Chen, Chun-Jung Chen	77
2-8 Liquid Scanner	
Hsiu-Hsiang Chen, C. K. Yen, Y. T. Li, W. D. Tyan, C. Fu	81
2-9 The development of a high performance, low cost package for MEMS Microphone package by using Lead-frame Land Grid Array (LLGA)	
Jiung-Yue Tien, His-Chen Yung, Min-Te Tu, Chin-Ching Huang	85

SESSION III : Assembly & Manufacturing

Session Chair: Andreas Ostmann (FhG-IZM, Germany)

3-2 Next Standard Packaging Method for DRAM - Chip-in-Substrate Package	
Cheng-Ta Ko*, Tao-Chih Chang, Chia-Wen Chiang, Tzu-Ying Kuo, Ying-Ching Shih	91
3-3 Green Certification for IC Package	
Jeffrey C.B. Lee	97
3-4 Underfill Assessments and Validations for Low-k FCBGA	
Nicholas Kao, Jeng Yuan Lai, Yu Po Wang, C.S. Hsiao	101
3-5 Sticking Effect on Cantilever Beam with Wetting Length of Liquid Less Than Beam Length after Spinning Drying	
Meng-Ju Lin	105
3-6 Impact of IMC Thickness on Lead-free Solder Joint Reliability under Thermal Aging: Ball Shear Tests vs. Cold Bump Pull Tests	
S. W. Ricky Lee, Fubin Song	109

SESSION IV : Industrial Session (ASE, Taiwan)

Session Chair: K.N. Chiang (NTHU, Taiwan)

4-1 Finite Element Analysis Procedure for Board-level Swept Sine Vibration Tests	
Chang-Lin Yeh, Yi-Shao Lai, Ching-Chun Wang	115
4-2 Nanoindentation-induced Phase Transformation of Silicon	
Ping-Feng Yang, Sheng-Rui Jian, Yi-Shao Lai, Tsan-Hsien Chen, Rong-Sheng Chen	119
4-3 A Numerical Study of Board-level Stacked-die Packages Under Coupled Power and Thermal Cycling Test Conditions	
Tong Hong Wang, Chang-Chi Lee, Ching-Chun Wang, Yi-Shao Lai	123

4-4 Ball Impact Responses of Wafer-level Chip-scale Packages	
Yi-Shao Lai, Hsiao-Chuan Chang, Chang-Lin Yeh	127
4-5 Effects of Photosensitive Film Sidewall Profile with Different Exposure Wavelength and Process Characteristics of Wafer Bump Technology	
Jui-i Yu*, Rick Yu, Tom Tai, Danial Huang, Walter Jau, Ker-Chang Hsieh, Adren Hsieh, Simon Su, Homing Tong	130
4-6 Bandpass Filters Design in the Organic Substrate without Using Large-Value Capacitors	
C.T. Chiu, C.L., Lin, T.S. Horng, P.N. Li, C.P. Hung	133

SESSION V : Model, Simulation & Design

Session Chair: Frank G. Shi (UCI, U.S.A.)

5-1 Light extraction from light-emitting diodes: effect of die geometries	
Nguyen T. Tran, Frank G. Shi	139
5-2 Distribution of Local Thermal Residual Stress in Thin Chips Stacked by Flip Chip Structures	
Hideo Miura, Nobuki Ueta, Yuhki Sato	143
5-3 A New Nano-Probe Using Micro Assembly Transfer	
Jen-Yi Chen, Chun-Te Lin, Wei-Chuan Liao, Hui Chi Su, Ching-Hsiang Tsai, Kuo-Ning Chiang	147
5-4 Reliability Analysis of a New Soft Joint Protection Technology Using in WLCSP	
Ming-Chih Yew, Shu-Ming Chang, Kuo-Ning Chiang	151
5-5 A Hybrid Modeling Technique for Circuit-Level Simulation of InGaAs, SiGe, and ZnSe-Ge HBT in RFIC and MPIC Systems	
Hsien-Cheng Tseng*, Jung-Hua Chou	155
5-6 Process-dependent Thermal-mechanical Analysis and Design of a Novel Nanowire-based Anisotropic Conductive Film Assembly	
Hsien-Chie Cheng, Chieh-Sheng Lin, Wen-Hwa Chen, Yung-Yue Hsu, Ruoh-Huey Uang	159
5-7 Lead-Free Flip Chip Package Reliability and the Finite Element-Factorial Design Methodology	
Chien-Chia Chiu, Chung-Jung Wu, Chih-Tang Peng, Kuo-Ning Chiang, Terry Ku, Kenny Cheng	163

SESSION VI : Material, Process & Equipment

Session Chair: Surasit Chungpaiboonpatana (Operations and Technology Mindspeed Inc.)

6-1 Interaction of Molding Compounds with Other Packaging Components and Their Effects on Electronics Packaging Design	
Michael Todd	169
6-2 C4NP - IBM Manufacturing & Reliability Data for Lead Free Flip Chip Solder Bumping	
Klaus Ruhmer, Eric Laine, Peter Gruber	173
6-3 Materials Challenges and Solutions for the Packaging of High Power LEDs	
Yuan-Chang Lin, Nguyen Tran, Yan Zhou, Yongzhi He, Frank G. Shi	177
6-4 Development of Wafer-Scale Sealing Test Using Different Size of Micro-resonators	
Hironao Okada, Toshihiro Itoh, Tadatoma Suga	181
6-5 Low Temperature Direct Bonding of Flip-Chip Mounting VCSEL to Si Substrate	
T. Imamura, E. Higurashi, T. Suga, R. Sawada	185

6-6 Highly Accelerated Life Test for the Reliability Assessment of the Lead-Free SMT Mainboard	
Wei Li, Rong-Chang Feng	189
6-7 ECR Plasma-Enhanced Au/Al Bondability in Fine-Pad-Pitch BGA Assembly	
Mu-Chun Wang, Yung-Chen Chen, Shuang-Yuan Chen, Heng-Sheng Huang	193
6-8 Perceptual Detection in Color Difference for Fragmental Panel of LCD	
Fu-Ming Tzu, Jung-Hua Chou	197
6-9 Development of Optimizing Process Flow and Materials Selection for Optical Device Packages	
Tzu-Yin Yen, Chung-Mao Yeh, Chin-Ching Huang, Min-Te Tu	201
Industrial Sponsors	208
Organization	209